

Product Change Notice (PCN)

件名: RL78/F13, F14 シリーズ Cu ワイヤ製品の前工程生産拠点追加

発行日: 9/29/2022

出荷開始予定日: 12/1/2023

改版履歴: 初版

変更内容の説明:

弊社マイコン製品 RL78/F13, F14 シリーズ Cu ワイヤ製品におきまして、前工程生産拠点の追加を計画しております。生産拠点の追加によりフレキシブルな生産を実施し、安定供給が可能となります。つきましては、お客様にご購入中の製品において、下記拠点の追加のご案内致しますのでご承知下さいますようお願い申し上げます。生産拠点におきましては、生産能力を考慮し弊社にて判断させていただきます。

- 1) ウェハプロセス拠点追加 : 那珂工場 Renesas Electronics Corporation (Naka Factory)
- 2) バックグラインド拠点追加: RSKL Renesas Semiconductor KL Sdn. Bhd. (RSKL)

対象製品リスト:

対象製品は下表 1 に示す RL78/F13, F14 シリーズ製品になります。詳細は付録をご参照ください。

表 1. 対象製品

	48pinLQFP (7x7/0.5)	64pinLQFP (10x10/0.5)	80pinLQFP (12x12/0.5)	100pinLQFP (14x14/0.5)
F13 Cu ワイヤ製品	○	○	○	—
F14 Cu ワイヤ製品	○	○	○	○

変更の理由:

製品の安定供給のため。

外形、実装、機能、品質、信頼性への影響:

外形 : 影響ありません
実装 : 影響ありません
機能 : 影響ありません
品質 : 影響ありません
信頼性 : 影響ありません

製品の識別方法:

マーク、ラベルまたは T/C コードにて識別可能です。T/C コードの内容は弊社営業へお問い合わせください。

信頼性データについて:

付録をご参照ください。

サンプル出荷予定日:

12/1/2022

製品/材料の化学物質データ:

弊社営業へお申しつけ下さい。

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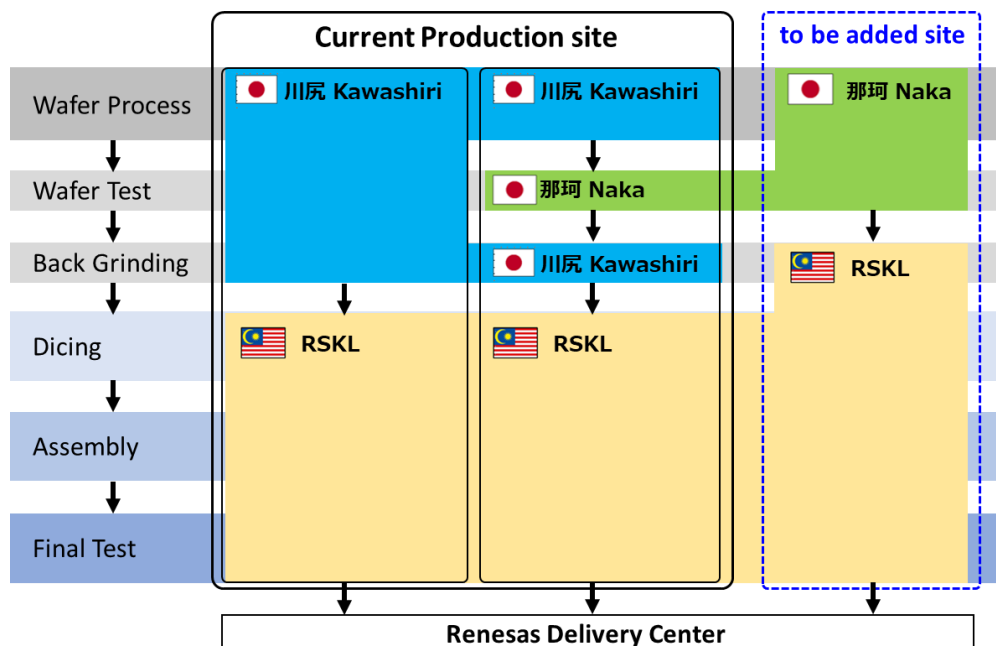
この通知に関するお問い合わせは、弊社営業、特約店までお願い致します。

付録

■製品仕様

項目		現状	展開
製品型名		変更なし	
前工程	拡散拠点	川尻	那珂
	プロセス	変更なし (MF3(130um)プロセス)	
	ウェハテスト拠点	変更なし (川尻/那珂)	
バックグラインド工程	バックグラインド拠点	川尻	RSKL
後工程	組立拠点	変更なし (RSKL)	
	ファイナルテスト拠点	変更なし (RSKL)	
	プロセス	変更なし (Cu ワイヤ)	
	外形	変更なし	
マーク		変更有り (本書 マーク仕様参照)	
ラベル		変更有り (本書 ラベル仕様参照)	

■生産フロー



■マーク仕様

Mark example for R5F10PPJCLFB (F14 Cu wire product)

	川尻品/Kawashiri (Cu wire)	那珂品/Naka (Cu wire)
example 48pin	10PPJCL XXXXXX4XX	10PPJCL XXXXXXEXX
example 64pin	R5F10PPJCL XXXXXX4XX	R5F10PPJCL XXXXXXEXX
example 80pin	R5F10PPJCL XXXXXX4XX MALAYSIA	R5F10PPJCL XXXXXXEXX MALAYSIA
example 100pin	R5F10PPJCL XXXXXX4XX MALAYSIA	R5F10PPJCL XXXXXXEXX MALAYSIA

※前工程拠点は赤字の箇所では判別可能です。

■ラベル仕様

Label example for R5F10PPJCLFB#15Q (F14 100pin Full-Carton)

川尻品/Kawashiri

Pb-Free T. RENESAS
MSL : 3

D/N R5F10PPJCLFB 15QP
SPN R5F10PPJCLFB#15Q 15QP

PID XXXXXXXXXXX-XXX
QTY 100
PCD XXXXXXXXXXX
T/C XXXX XXXXXX4XX
S.LOT XXX-XXXXX

2020/07/10
MC: JPMYMY
ASSEMBLED IN MALAYSIA
FROM WAFERS OF JAPAN



那珂品/Naka

Pb-Free T. RENESAS
MSL : 3

D/N R5F10PPJCLFB 1AQP
SPN R5F10PPJCLFB#1AQ 1AQP

PID XXXXXXXXXXX-XXX
QTY 100
PCD XXXXXXXXXXX
T/C XXXX XXXXXXEXX
S.LOT XXX-XXXXX

2020/07/10
MC: JPMYMY
ASSEMBLED IN MALAYSIA
FROM WAFERS OF JAPAN



※前工程拠点は赤字の箇所では判別可能です。

R5F10PPGCLFB#15Q	R5F10PPGCLFB#1AQ	R5F10PPGCLFB#3AQ	F14	128kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPGCLFB#35	R5F10PPGCLFB#3A	R5F10PPGCLFB#3A	F14	128kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPGCLFB#35Q	R5F10PPGCLFB#3AQ	R5F10PPGCLFB#3AQ	F14	128kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPGCLFB#55	R5F10PPGCLFB#5A	R5F10PPGCLFB#3A	F14	128kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPGCLFB#55Q	R5F10PPGCLFB#5AQ	R5F10PPGCLFB#3AQ	F14	128kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPHCKFB#15	R5F10PPHCKFB#1A	R5F10PPHCKFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPHCKFB#15Q	R5F10PPHCKFB#1AQ	R5F10PPHCKFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPHCKFB#35	R5F10PPHCKFB#3A	R5F10PPHCKFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPHCKFB#35Q	R5F10PPHCKFB#3AQ	R5F10PPHCKFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPHCKFB#55	R5F10PPHCKFB#5A	R5F10PPHCKFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPHCKFB#55Q	R5F10PPHCKFB#5AQ	R5F10PPHCKFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPHCLFB#15	R5F10PPHCLFB#1A	R5F10PPHCLFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPHCLFB#15Q	R5F10PPHCLFB#1AQ	R5F10PPHCLFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPHCLFB#35	R5F10PPHCLFB#3A	R5F10PPHCLFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPHCLFB#35Q	R5F10PPHCLFB#3AQ	R5F10PPHCLFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPHCLFB#55	R5F10PPHCLFB#5A	R5F10PPHCLFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPHCLFB#55Q	R5F10PPHCLFB#5AQ	R5F10PPHCLFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPJCKFB#15	R5F10PPJCKFB#1A	R5F10PPJCKFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPJCKFB#15Q	R5F10PPJCKFB#1AQ	R5F10PPJCKFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPJCKFB#35	R5F10PPJCKFB#3A	R5F10PPJCKFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPJCKFB#35Q	R5F10PPJCKFB#3AQ	R5F10PPJCKFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPJCKFB#55	R5F10PPJCKFB#5A	R5F10PPJCKFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPJCKFB#55Q	R5F10PPJCKFB#5AQ	R5F10PPJCKFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPJCLFB#15	R5F10PPJCLFB#1A	R5F10PPJCLFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPJCLFB#15Q	R5F10PPJCLFB#1AQ	R5F10PPJCLFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPJCLFB#35	R5F10PPJCLFB#3A	R5F10PPJCLFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPJCLFB#35Q	R5F10PPJCLFB#3AQ	R5F10PPJCLFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPJCLFB#55	R5F10PPJCLFB#5A	R5F10PPJCLFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPJCLFB#55Q	R5F10PPJCLFB#5AQ	R5F10PPJCLFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Tape&Reel

Report No. MCR-22-0668

Date: 28/Sep./2022

RENESAS SEMICONDUCTOR RELIABILITY REPORT

SERIES : RL78/F13,F14

DEVICE : [対象製品リスト] をご参照ください

APPLICATION : Automobile

<ウエハ製造工場>

ルネサス セミコンダクタ マニュファクチュアリング株式会社 那珂工場

<組立工場>

Renesas Semiconductor KL Sdn. Bhd.

Quality Assurance Div.
Renesas Electronics Corporation

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(Rev.5.0-2 October 2020)

Q100 Qualification Test Results

[信頼性試験は(拡散プロセス/拡散工場),(パッケージ構造/組立工場)を考慮した代表製品で実施しております。]

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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TEST GROUP A – ACCELERATED ENVIRONMENT STRESS TESTS

PC	A1	JESD22 A113 J-STD-020	Preconditioning: (Test @ Rm) SMD only; Moisture Preconditioning for THB/HAST, AC/UHST, TC, &PTC ; Peak Reflow Temp=260°C	Min.MSL=3			MSL=3	-
THB or HAST	A2	JESD22 A101	Temperature Humidity Bias: (Test @ Rm/Hot) Ta=85°C, RH=85%, 1000hrs	3	77	231	0 of 231	-
AC or UHST or TH	A3	JESD22 A118	Unbiased Highly Accelerated Stree Test: (Test @ Rm) Ta=110°C, 85% RH, 264h	3	77	231	0 of 231	-
TC	A4	JESD22 A104	Temperature Cycle: (Test @ Hot) Ta=-65°C to 150°C, 500cyc Wire Bond Pull: (0 Fails after TC)	3	77	231	0 of 231 0 Fails after TC (WBP)	-
PTC	A5	JESD22 A105	Power Temperature Cycle: (Test @ Rm/Hot) -	-	-	-	-	N/A
HTSL	A6	JESD22 A103	High Temperature Storage Life: (Test @ Rm/Hot) Ta=150°C, 1000hrs	3	45	135	0 of 135	-

TEST GROUP B – ACCELERATED LIFETIME SIMULATION TESTS

HTOL	B1	JESD22 A108	High Temp Operating Life: (Test @ Rm/Cold/Hot) Ta=125°C, 1000hrs	3	77	231	0 of 231	-	
ELFR	B2	AEC-Q100-008	Early Life Failure Rate: (Test @ Rm/Hot) Ta=125°C, 48hrs	3	800	2400	0 of 2400	-	
EDR	B3	AEC-Q100-005	NVM Endurance & Data Retention Test: (Test @ Rm/Hot)	For HTOL	3	77	231	0 of 231	-
				For HTSL	3	45	135	0 of 135	-

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Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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TEST GROUP C – PACKAGE ASSEMBLY INTEGRITY TESTS

WBS	C1	AEC-Q100-001 AEC-Q003	Wire Bond Shear Test: (Cpk > 1.67)	30 bonds	5 parts Min.	30 bonds	0 of 30bonds	Cpk>1.67
WBP	C2	Mil-STD-883 Method 2011 AEC-Q003	Wire Bond Pull: (Cpk > 1.67); Each bonder used	30 bonds	5 parts Min.	30 bonds	0 of 30bonds	Cpk>1.67
SD	C3	JESD22 B102 JSTD-002D	Solderability: (>95% coverage) 8 hr steam aging prior to testing	1	15	15	0 of 15	-
PD	C4	JESD22 B100, JESD22 B108 AEC-Q003	Physical Dimensions: (Cpk > 1.67)	3	10	30	0 of 30	Cpk>1.67
SBS	C5	AEC-Q100-010 AEC-Q003	Solder Ball Shear: (Cpk > 1.67); 5 balls from min. of 10 devices	-	-	-	-	N/A
LI	C6	JESD22 B105	Lead Integrity: (No lead cracking or breaking); Through-hole only; 10 leads from each of 5 devices	-	-	-	-	N/A

TEST GROUP D – DIE FABRICATION RELIABILITY TESTS

EM	D1	JESD61	Electromigration:	-	-	-	Pass	Confirmed by process TEG
TDDB	D2	JESD35	Time Dependant Dielectric Breakdown:	-	-	-	Pass	Confirmed by process TEG
HCI	D3	JESD60 & 28	Hot Carrier Injection:	-	-	-	Pass	Confirmed by process TEG
NBTI	D4	JESD90	Negative Bias Temperature Instability:	-	-	-	Pass	Confirmed by process TEG
SM	D5	JESD61,87 & 202	Stress Migration:	-	-	-	Pass	Confirmed by process TEG

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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TEST GROUP E- ELECTRICAL VERIFICATION

TEST	E1	User/Supplier Specification	Pre and Post Stress Electrical Test:	All	All	All	0 of All	-
HBM	E2	AEC-Q100-002	Electrostatic Discharge, Human Body Model: (Test @ Rm/Hot); (2KV HBM / Class 2 or better)	1	3	3	0 of 3 ESD Level= HBM:2	HBM>2KV
CDM	E3	AEC-Q100-011	Electrostatic Discharge, Charged Device Model: (Test @ Rm/Hot); (750V corner leads, 500V all other leads / Class C4B or better)	1	3	3	0 of 3 ESD Level= CDM:C4B	Corner leads: 750V Pass All other leads:500V Pass
LU	E4	AEC-Q100-004	Latch-Up: (Test @ Rm/Hot)	1	6	6	0 of 6	-
ED	E5	AEC-Q100-009 AEC-Q003	Electrical Distributions: (Test @ Rm/Hot/Cold) (where applicable, Cpk>1.67)	3	30	90	0 of 90	-
FG	E6	AEC-Q100-007	Fault Grading:	-	-	-	>98%	-
CHAR	E7	AEC-Q003	Characterization: (Test @ Rm/Hot/Cold)	-	-	-	Pass	According to Renesas standard procedure
EMC	E9	SAE J1752/3	Electromagnetic Compatibility (Radiated Emissions)	1	1	1	0 of 1	-
SC	E10	AEC Q100-012	Short Circuit Characterization	-	-	-	-	N/A
SER	E11	JESD89-1 JESD89-2 JESD89-3	Soft Error Rate	-	-	-	Pass	Performed by process TEG
LF	E12	AEC-Q005	Lead (Pb) Free: (see AEC-Q005)	-	-	-	Pass	Solderability: See SD (C3) result. Solder heat resistance: N/A (Wave Solder is Not recommended.) Whisker: Performed on product TEG with test method based on JESD201.

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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TEST GROUP F – DEFECT SCREENING TESTS

PAT	F1	AEC-Q001	Process Average Testing: (see AEC-Q001)	All	All	All	Reject units outside PAT limits	Apply to mass production according to Renesas standard procedure
SBA	F2	AEC-Q002	Statistical Bin/Yield Analysis: (see AEC-Q002)	All	All	All	Reject units outside criteria	Apply to mass production according to Renesas standard procedure

TEST GROUP G – CAVITY PACKAGE INTEGRITY TESTS (for Ceramic Package testing only)

MS	G1	JESD22 B104	Mechanical Shock: (Test @ Rm)	-	-	-	-	N/A
VFV	G2	JESD22 B103	Variable Frequency Vibration: (Test @ Rm)	-	-	-	-	N/A
CA	G3	MIL-STD-883 Method 2001	Constant Acceleration: (Test @ Rm)	-	-	-	-	N/A
GFL	G4	MIL-STD-883 Method 1014	Gross and Fine Leak:	-	-	-	-	N/A
DROP	G5	-----	Drop Test: (Test @ Rm) MEMS cavity parts only. Drop part on each of 6 axes once from a height of 1.2m onto a concrete surface.	-	-	-	-	N/A
LT	G6	MIL-STD-883 Method 2004	Lid Torque:	-	-	-	-	N/A
DS	G7	MIL-STD-883 Method 2019	Die Shear:	-	-	-	-	N/A
IWV	G8	MIL-STD-883 Method 1018	Internal Water Vapor:	-	-	-	-	N/A

Calculation method of standard failure rate

Target : 0.13um CMOS process product (RL78 series Automobile)

Operating reliability is decided by inherent reliability of device and environment condition of use (See below).

Calculation method of standard failure rate (λ)

$$\lambda = \lambda_b \times \pi T \quad (\text{FIT})$$

λ_b → (1) Basic failure rate
 πT → (2) Temperature parameter

(1) Basic failure rate (λ_b)

λ_b : 0.18 (FIT)

(2) Temperature parameter

$$\pi T = \exp \left\{ 11600 \times E_a \times \left(\frac{1}{273+55} - \frac{1}{273+T_a} \right) \right\}$$

E_a : Activation energy (eV)

T_a : ambient temperature

πT Simplified chart ($E_a=0.7\text{eV}$)												
$T_a(^{\circ}\text{C})$	40	50	55	60	65	70	75	80	85	90	100	110
πT	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

-Confidence level 60% -Standard temperature $T_a=55^{\circ}\text{C}$

(3) MTTF (Mean Time To Failure)

$$\text{MTTF} = \frac{1}{\lambda}$$

対象製品リスト

[RL78/F13,F14 series]

R5F10PPJCLFB	R5F10BMGCLFB	R5F10AMGCLFB
R5F10PPJCKFB	R5F10BMGCKFB	R5F10AMGCKFB
R5F10PPHCLFB	R5F10BMFCLFB	R5F10AMFCLFB
R5F10PPHCKFB	R5F10BMFCKFB	R5F10AMFCKFB
R5F10PPGCLFB	R5F10BMECLFB	R5F10AMECLFB
R5F10PPGCKFB	R5F10BMECKFB	R5F10AMECKFB
R5F10PPFCLFB	R5F10BLGCLFB	R5F10ALGCLFB
R5F10PPFCKFB	R5F10BLGCKFB	R5F10ALGCKFB
R5F10PPECLFB	R5F10BLFCLFB	R5F10ALFCLFB
R5F10PPECKFB	R5F10BLFCKFB	R5F10ALFCKFB
R5F10PMJCLFB	R5F10BLECLFB	R5F10ALECLFB
R5F10PMJCKFB	R5F10BLECKFB	R5F10ALECKFB
R5F10PMHCLFB	R5F10BLDCLFB	R5F10ALDCLFB
R5F10PMHCKFB	R5F10BLDCKFB	R5F10ALDCKFB
R5F10PMGCLFB	R5F10BLCCLFB	R5F10ALCCLFB
R5F10PMGCKFB	R5F10BLCCKFB	R5F10ALCCKFB
R5F10PMFCLFB	R5F10BGGCLFB	R5F10AGGCLFB
R5F10PMFCKFB	R5F10BGGCKFB	R5F10AGGCKFB
R5F10PMECLFB	R5F10BGFCLFB	R5F10AGFCLFB
R5F10PMECKFB	R5F10BGFCKFB	R5F10AGFCKFB
R5F10PLJCLFB	R5F10BGECLFB	R5F10AGECLFB
R5F10PLJCKFB	R5F10BGECKFB	R5F10AGECKFB
R5F10PLHCLFB	R5F10BGDCLFB	R5F10AGDCLFB
R5F10PLHCKFB	R5F10BGDCKFB	R5F10AGDCKFB
R5F10PLGCLFB	R5F10BGCCLFB	R5F10AGCCLFB
R5F10PLGCKFB	R5F10BGCCKFB	R5F10AGCCKFB
R5F10PLFCLFB		R5F10AGACLFB
R5F10PLFCKFB		R5F10AGACKFB
R5F10PLECLFB		
R5F10PLECKFB		
R5F10PGJCLFB		
R5F10PGJCKFB		
R5F10PGHCLFB		
R5F10PGHCKFB		
R5F10PGGCLFB		
R5F10PGGCKFB		
R5F10PGFCLFB		
R5F10PGFCKFB		
R5F10PGECLFB		
R5F10PGECKFB		
R5F10PGDCLFB		
R5F10PGDCKFB		